

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.44	100.0	6.3
			Subtotal	0.44	100	6.3
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01	100.0	0.15
	Pure metal	Aluminium (Al)	7429-90-5	0.16	100.0	2.34
			Subtotal	0.17	200	2.49
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.74	100.0	25
			Subtotal	1.74	100	25
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02	0.04	0.34
	Copper alloy	Iron (Fe)	7439-89-6	0.06	0.1	0.84
	Copper alloy	Copper (Cu)	7440-50-8	58.26	99.86	838.82
			Subtotal	58.34	100	840
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	3.4	8.7	48.94
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	6.25	16.0	90
	Filler	Silica fused	60676-86-0	29.31	75.0	421.88
	Carbon Black	Carbon black	1333-86-4	0.12	0.3	1.69
			Subtotal	39.08	100	562.51
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.01	5.0	0.16
	Lead alloy	Silver (Ag)	7440-22-4	0.01	2.5	0.08
	Lead alloy	Lead (Pb)	7439-92-1	0.21	92.5	3.01
			Subtotal	0.23	100	3.25
			Total	100	100	1439.55

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